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Vishay Siliconix

Dual N-Channel 20 V (D-S) MOSFET



Marking code: PE

PRODUCT SUMMARY				
V _{DS} (V)	20			
$R_{DS(on)}$ max. (Ω) at V_GS = 4.5 V	0.235			
$R_{DS(on)}$ max. (Ω) at V_GS = 2.5 V	0.306			
Q _g typ. (nC)	0.9			
I _D (A) ^a	1.1			
Configuration	Dual			

FEATURES

- TrenchFET® power MOSFET
- 100 % R_g tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Load switch and DC/DC converter for portable devices
- High speed switching



N-Channel MOSFET

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N-Channel MOSFET

ORDERING INFORMATION				
Package	SC-70			
Lead (Pb)-free and halogen-free	Si1902CDL-T1-GE3			

ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	20	V	
Gate-source voltage		V _{GS}	± 12	v	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		1.1		
	T _C = 70 °C		0.9		
	T _A = 25 °C	I _D	1 b, c		
	T _A = 70 °C		0.8 ^{b, c}	A	
Pulsed drain current (t = 300 µs)		I _{DM}	2		
	T _C = 25 °C		0.35		
Continuous source-drain diode current	T _A = 25 °C	IS	0.25 ^{b, c}		
Maximum power dissipation	T _C = 25 °C		0.42		
	T _C = 70 °C		0.27	w	
	T _A = 25 °C	PD	0.30 ^{b, c}	VV	
	T _A = 70 °C		0.23 ^{b, c}		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, d	t≤5 s	R _{thJA}	290	350	°C/W	
Maximum junction-to-foot (drain)	Steady state	R _{thJF}	250	300	0/10	

Notes

a. Based on $T_C = 25 \ ^{\circ}C$

b. Surface mounted on 1" x 1" FR4 board

c. t = 5 s

d. Maximum under steady state conditions is 410 $^{\circ}\text{C/W}$

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	· ·		<u> </u>				
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	20	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	L 050 A	-	25	-	mV/°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-2.6	-		
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	0.6	-	1.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 12 V$	-	-	± 100	nA	
7		$V_{DS} = 20 V, V_{GS} = 0 V$	-	-	1	<u> </u>	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 85 ^{\circ}\text{C}$	-	-	10	μA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}$	2	-	-	А	
D · · · · · ·		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 1 \text{ A}$	-	0.195	0.235		
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 0.3 \text{ A}$	-	0.255	0.306	Ω	
Forward transconductance	g _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ A}$	-	3	-	ms	
Dynamic ^b			•	•	1	1	
Input capacitance	C _{iss}		-	62	-	pF	
Output capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	-	20	-		
Reverse transfer capacitance	C _{rss}		-	7	-		
•		$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ A}$	-	2	3	-	
Total gate charge	Qg		-	0.9	1.4		
Gate-source charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1 \text{ A}$	-	0.2	-		
Gate-drain charge	Q _{gd}		-	0.2	-		
Gate resistance	Ra	f = 1 MHz	2.4	12	24	Ω	
Turn-on delay time	t _{d(on)}		-	4	8		
Rise time	tr	V_{DD} = 10 V, R_L = 12.5 Ω	-	13	20	1	
Turn-off delay time	t _{d(off)}	$I_D \cong 0.8 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_g = 1 \Omega$	-	11	20		
Fall time	t _f		-	9	18	İ	
Turn-on delay time	t _{d(on)}		-	6	12	İ	
Rise time	t _r	V_{DD} = 10 V, R_L = 12.5 Ω	-	16	24	ns	
Turn-off delay time	t _{d(off)}	$I_D \cong 0.8 \text{ A}, V_{GEN} = 4.5 \text{ V}, \text{ R}_g = 1 \Omega$	-	13	20		
Fall time	t _f		-	10	20		
Drain-Source Body Diode Characteris	tics		<u> </u>				
Continuous source-drain diode current	IS	T _C = 25 °C	-	-	0.35		
Pulse diode forward current ^a	I _{SM}			-	2	A	
Body diode voltage	V _{SD}	I _S = 0.8 A	-	0.8	1.2	V	
Body diode reverse recovery time	t _{rr}		-	2	4	nC	
Body diode reverse recovery charge	Q _{rr}		-	8	16		
Reverse recovery fall time	t _a	I _F = 0.8 A, di/dt = 100 A/μs	-	5	-	ns	
Reverse recovery rise time	t _b		-	3	-	1	

Notes

a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2\%$

b. Guaranteed by design, not subject to production testing

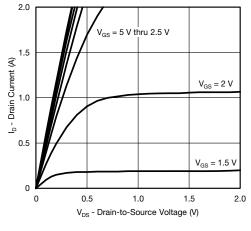
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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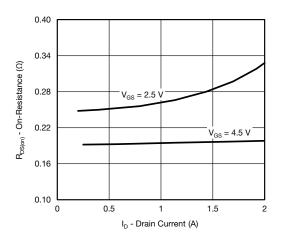


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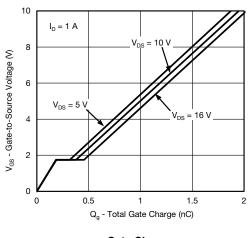
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



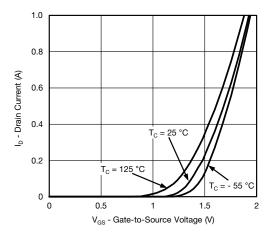
Output Characteristics



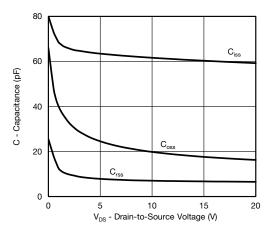
On-Resistance vs. Drain Current and Gate Voltage



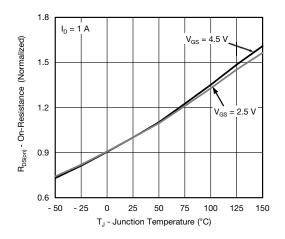
Gate Charge



Transfer Characteristics



Capacitance



On-Resistance vs. Junction Temperature

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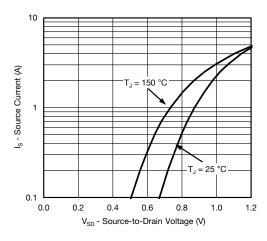
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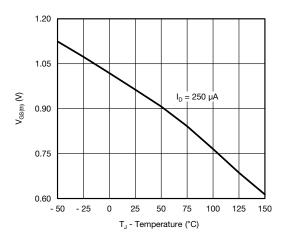


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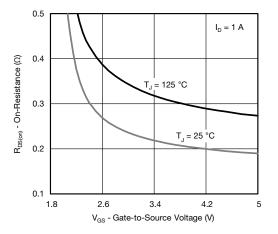
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



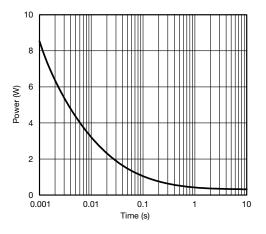
Source-Drain Diode Forward Voltage



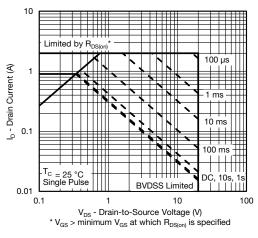




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power (Junction-to-Ambient)



Safe Operating Area, Junction-to-Ambient

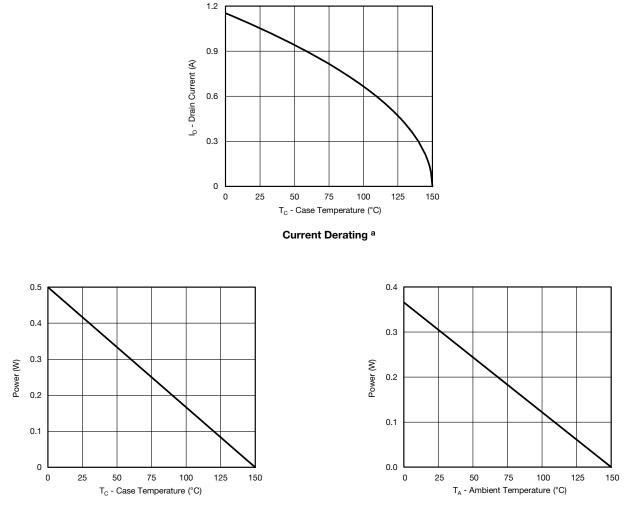
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Power Derating, Junction-to-Foot

Power Derating, Junction-to-Ambient

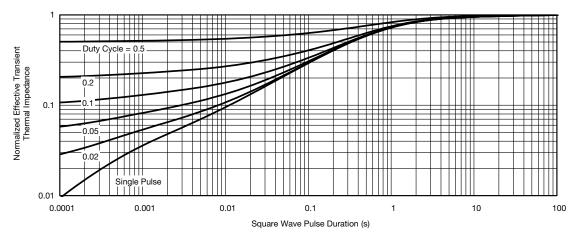
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

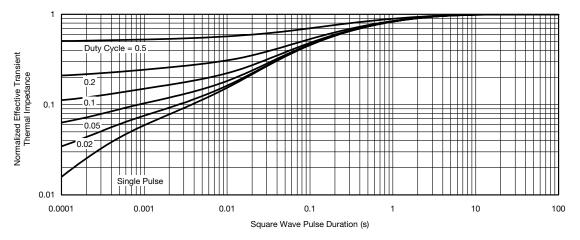


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for silicon technology and package reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?67876.

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